

TMX320DM368 Digital Video Evaluation Module

This digital video evaluation module (DVEVM) guide allows users to run the basic board and setup verification by displaying video passed from source content through the EVM to the display.



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Introduction www.ti.com

1 Introduction

The DVEVM contains the following:

- DM368 EVM target board
- Power cable
- Serial cable
- Ethernet cable
- 8-GB micro SD card with SD adapter and USB card reader
- Linux support package software development kit (uSD card)
- DM368 EVM technical reference manual (soft copy on uSD Card)



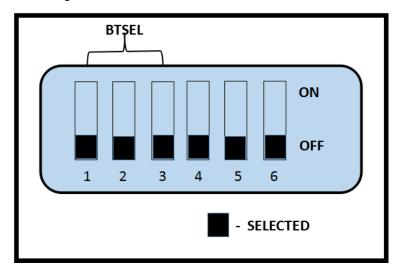
Figure 1. DM368 DVEVM Board



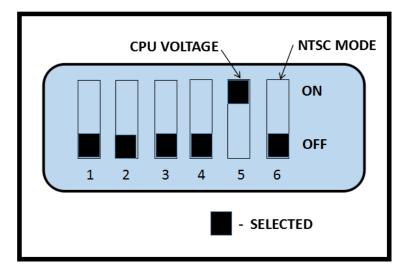
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2 Hardware Setup

1. Verify DIP SW4 is configured to NAND boot mode.



2. Verify DIP SW5 is configured to 1.35-V core voltage mode and component video output mode.



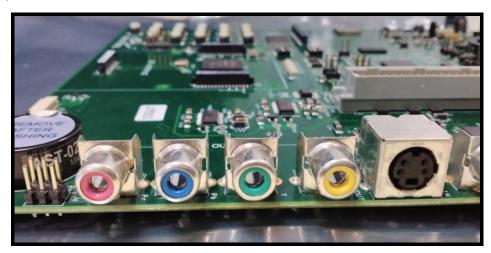


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3. Connect a video source (camera, blue ray DVD player, and so forth) to the component video in the RCA connector. Power on your video source.



4. Connect your HD video display to the component video out RCA connector. Power on the HD video display.





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5. Connect an audio speaker to stereo line out and an audio source to stereo line in.



6. Connect power cable to the DVEVM power jack on the board. To be ESD safe, plug in the other end of cable only after you have connected the power cord to the board.



7. You should now see video playing on your connected HD video display that has been passed through the EVM from video source.



3 Additional Connection Capability Information

If you are using the Ethernet connection, connect the provided Ethernet cable to the Ethernet port on the EVM board and to an Ethernet network port.





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